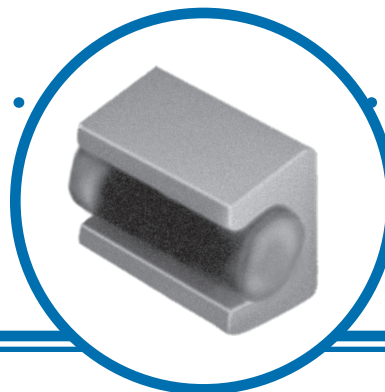


# Metal Glaze™ Power Pack Surface Mount High Power Density Ceramic Package



## PPS-1 Series

- Low inductance
- 0.1Ω to 348KΩ range
- Superior surge handling capability
- 150°C maximum operating temperature
- 1 Watt performance - standard 2010 footprint
- Flameproof ceramic package provides superior temperature rise profile

## Electrical Data

Size	IRC Type	Maximum Power Rating	Working Voltage <sup>1</sup>	Maximum Voltage	Resistance Range (ohms)	Tolerance (±%) <sup>2</sup>	TCR (ppm/°C) <sup>2</sup>
2010	PPS-1	1W	350	700	0.1 to 0.99	1, 2, 5	100
					1.0 to 348K	1, 2, 5	50, 100

<sup>1</sup>Not to exceed ( $\sqrt{P \times R}$ )<sup>2</sup>. <sup>2</sup>Consult factory for tighter tolerances and TCRs.

## Applications

The PPS-1 will dissipate 1 watt at 70°C on a 2010 footprint. The PPS-1 is recommended for applications where board real estate or component/board TCE mismatch is a major concern. It is also recommended in circuits where a standard 2010 resistor exhibits marginal or unacceptable performance due to high power density/surge handling demands.

## Environmental Data

Characteristic	Maximum Change	Test Method
<b>Thermal Shock</b>	±(0.5% + 0.01 ohm)	MIL-R-55342E Par 4.7.3 (-65°C + 150°C, 5 cycles)
<b>Low Temperature Operation</b>	±(0.25% + 0.01 ohm)	MIL-R-55342E Par 4.7.4 (-65°C @ working voltage)
<b>Short Time Overload</b>	±(1.0% + 0.01 ohm)	MIL-R-55342E Par 4.7.5 (2.5 x (PxR)) <sup>1/2</sup>
<b>High Temperature Exposure</b>	±(0.5% + 0.01 ohm)	MIL-R-55342E Par 4.7.6 (+150°C for 100 hours)
<b>Resistance to Bonding Exposure</b>	±(0.25% + 0.01 ohm)	MIL-R-55342E Par 4.7.7 (Reflow soldered to board @ 260°C for 10 seconds)
<b>Solderability</b>	95% minimum coverage	MIL-STD-202, Method 208 (245°C for 5 seconds)
<b>Moisture Resistance</b>	±(0.5% + 0.01 ohm)	MIL-R-55342E Par 4.7.8 (10 cycles, total 240 hours)
<b>Life Test</b>	±(1.0% + 0.01 ohm)	MIL-R-55342E Par 4.7.10 (2000 hours @ 70°C intermittent)
<b>Terminal Adhesion Strength</b>	±(1% + 0.01 ohm)	1200 gram push from underside of mounted chip for 60 seconds
<b>Resistance to Board Bending</b>	±(1% + 0.01 ohm)	Chip mounted in center of 90mm long board, deflected 5mm so as to exert pull on chip contacts for 10 seconds

### General Note

IRC reserves the right to make changes in product specification without notice or liability. All information is subject to IRC's own data and is considered accurate at time of going to print.

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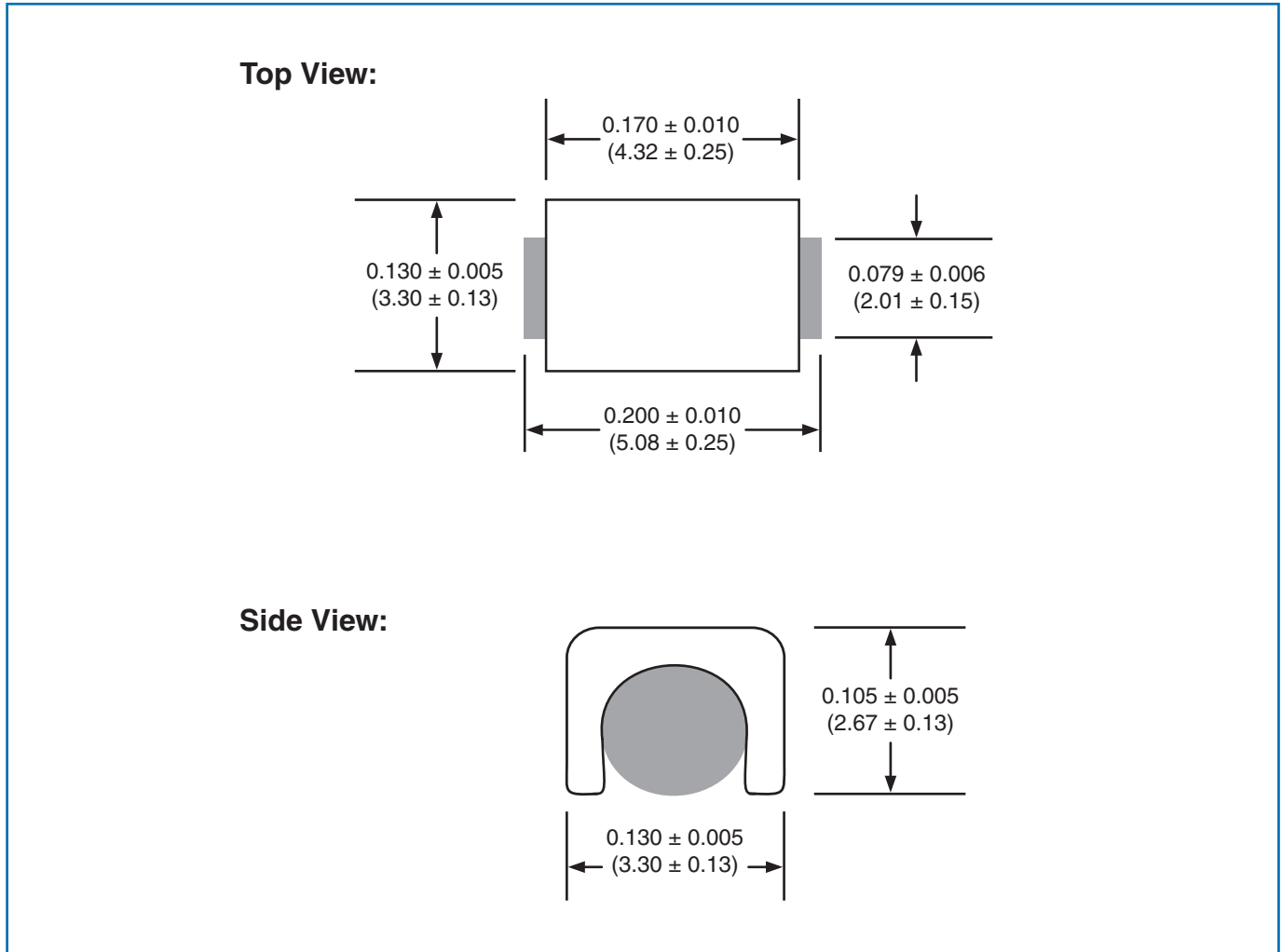


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## Physical Data (Inches and (mm))



## Ordering Data

